



Material Content Data Sheet



Sales Product Name		BFP 640 H6327		Issued		29. August 2013		
MA#		MA000843522						
Package		PG-SOT343-4-2		Weight*		7.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		274	
	non noble metal	tin	7440-31-5	0.001	0.01		71	
	inorganic material	silicon	7440-21-3	0.017	0.24	0.28	2388	2732
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		97	
	non noble metal	titanium	7440-32-6	0.003	0.05		485	
	non noble metal	chromium	7440-47-3	0.010	0.15		1456	
	non noble metal	copper	7440-50-8	3.433	48.31	48.52	483304	485342
wire	noble metal	gold	7440-57-5	0.010	0.14	0.14	1352	1352
encapsulation	organic material	carbon black	1333-86-4	0.030	0.42		4216	
	plastics	epoxy resin	-	0.644	9.07		90652	
	inorganic material	silicondioxide	60676-86-0	2.321	32.68	42.17	326768	421636
leadfinish	non noble metal	tin	7440-31-5	0.199	2.80	2.80	28047	28047
plating	noble metal	silver	7440-22-4	0.433	6.09	6.09	60890	60891
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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